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(12) **United States Design Patent**
Sawada

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(54) **POWER SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

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(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

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361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 253;
438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 2021/00; H01L 2021/02; H01L
2021/04; H01L 21/4814; H01L 21/4846;
H01L 21/4871; H01L 21/67144; H01L
23/02; H01L 23/13; H01L 23/14; H01L
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2924/1711; H01L 2924/1715; H01L
2924/17151; H01L 2924/181; H01L
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2224/08054; H01L 23/58; H05B 41/14;
H02B 6/4201; G02B 6/4256; G02B
6/4257; G02B 6/4261; G02B 6/4262;
G02B 6/428; G02B 6/4281; H05K 1/14;
H05K 1/141; H05K 1/142; H05K 1/144;
H05K 1/18; H05K 1/181; H05K 1/182;
H05K 1/026

See application file for complete search history.

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(57) **CLAIM**

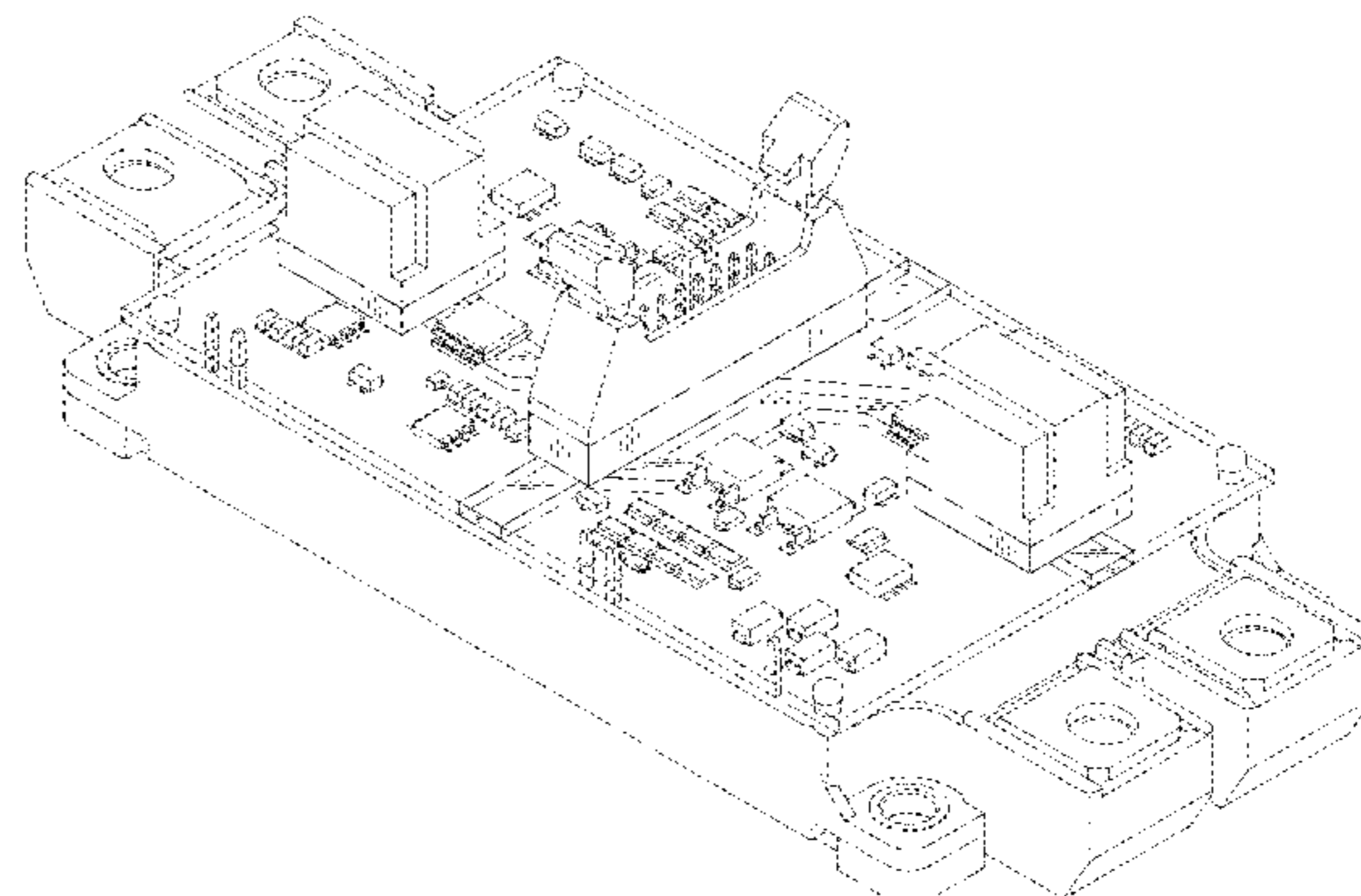
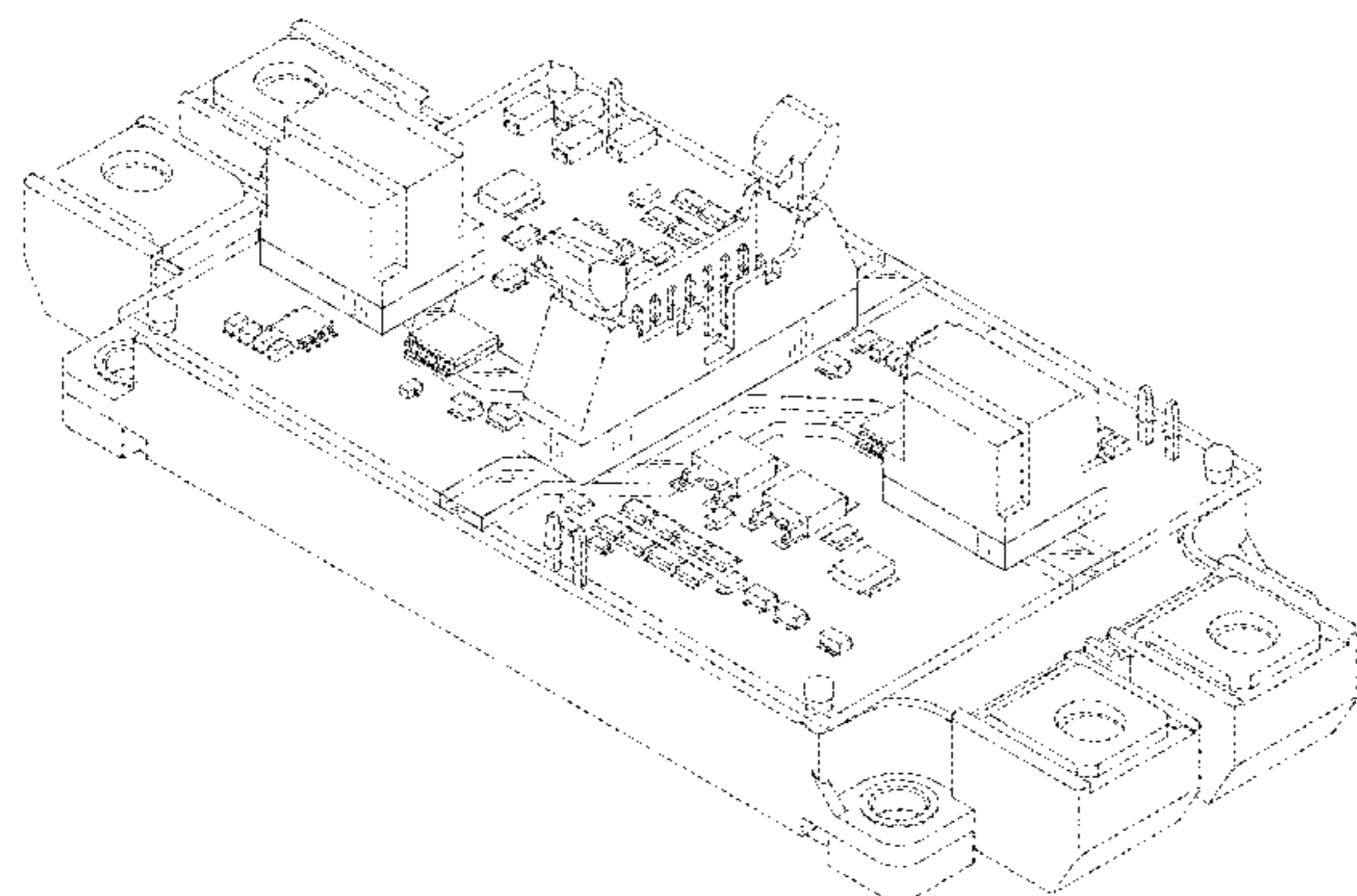
The ornamental design for a power semiconductor module,
as shown and described.

DESCRIPTION

FIG. 1 is a front, top, and right side perspective view of a
power semiconductor module showing my new design;
FIG. 2 is a rear, top, and left side perspective view thereof;
FIG. 3 is a front view thereof;
FIG. 4 is a rear view thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof;
FIG. 7 is a right side view thereof; and,
FIG. 8 is a left side view thereof.

The features shown in broken lines in the drawings depict
portions of the article that form no part of the claimed
design. The dash-dotted lines denote the boundary of the
claim and form no part of the claimed design. The oblique
line shading shown in the drawings indicates a transparent
surface.

1 Claim, 8 Drawing Sheets



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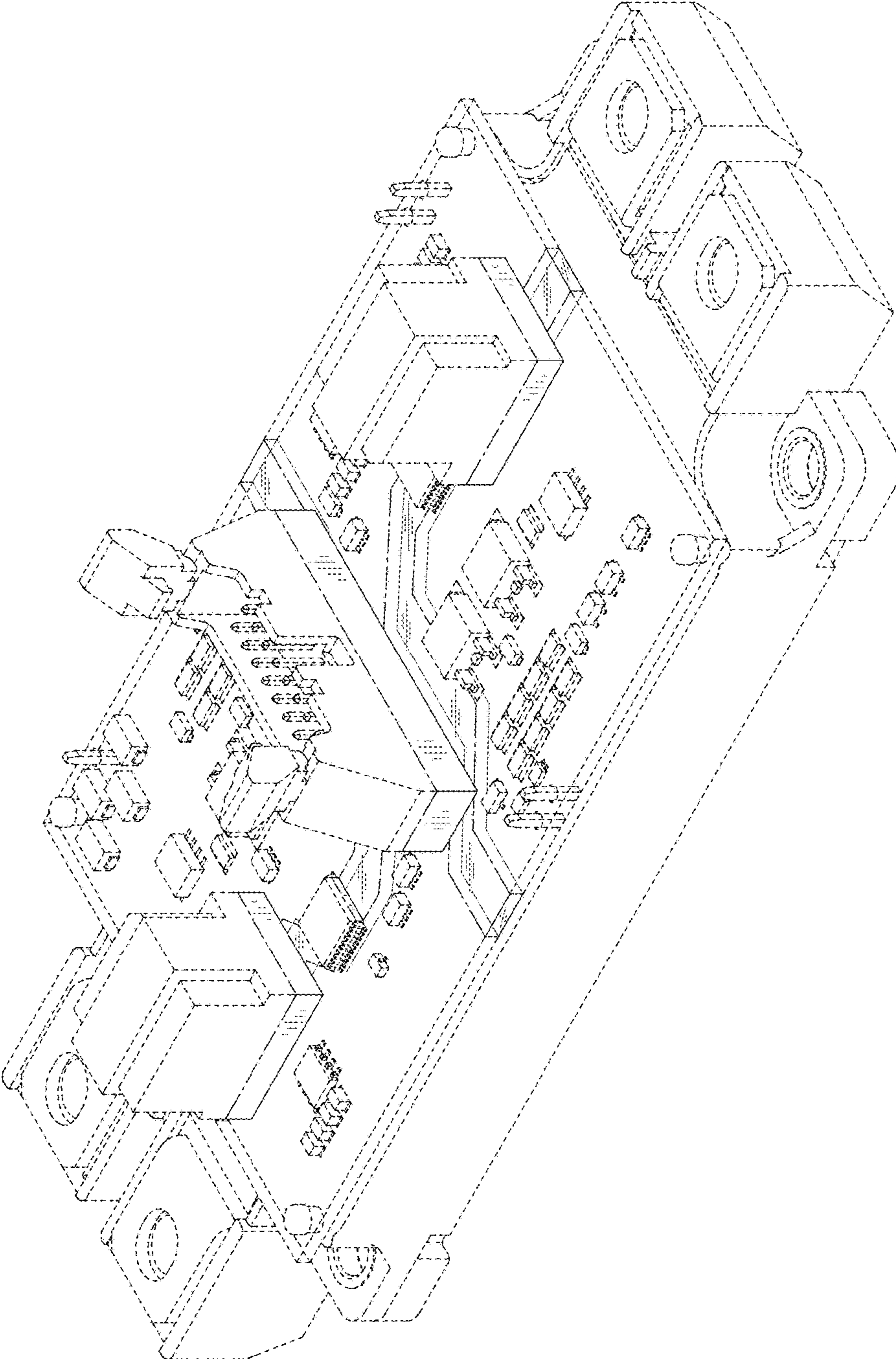


FIG.1

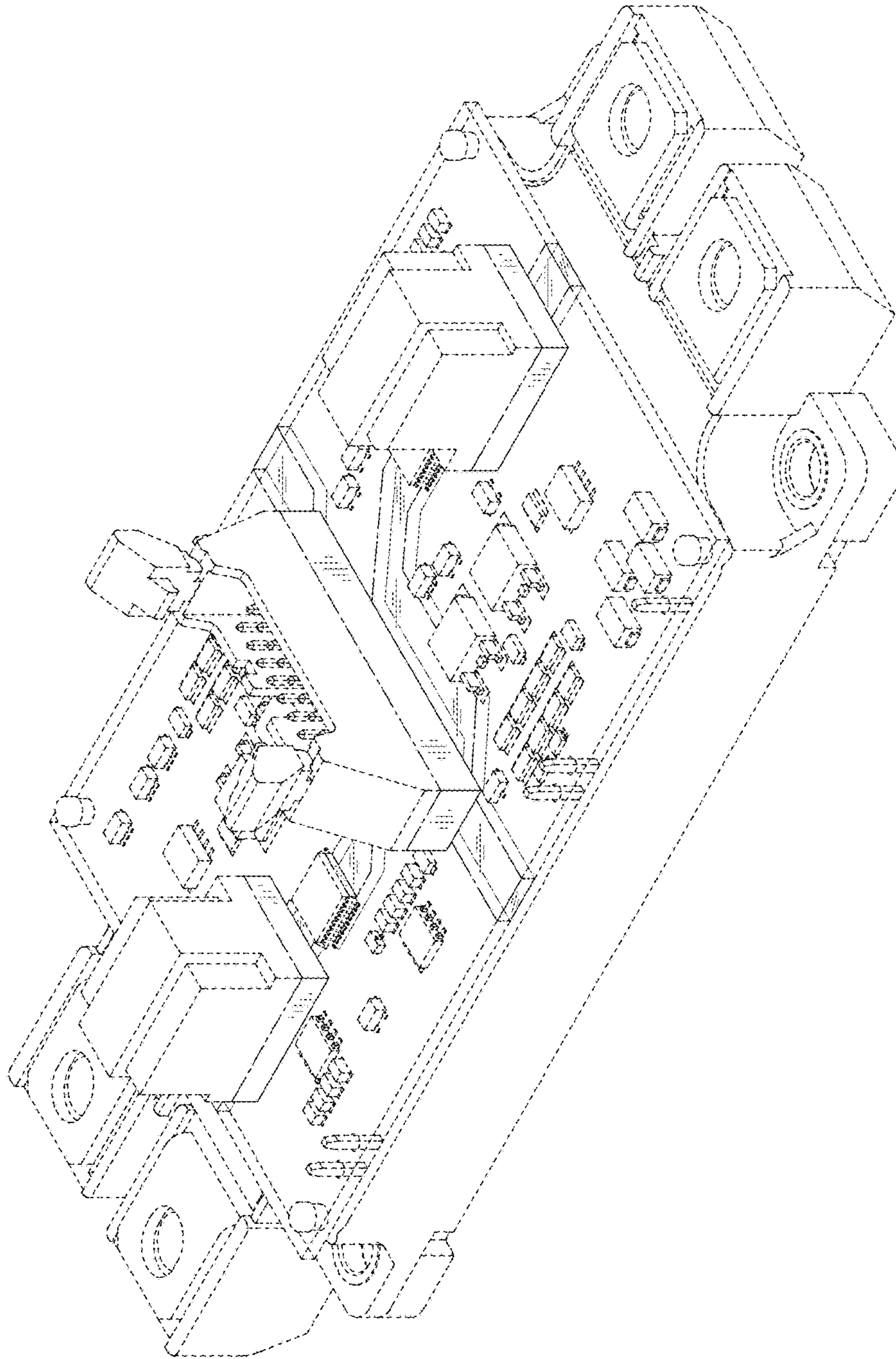


FIG.2

FIG.3

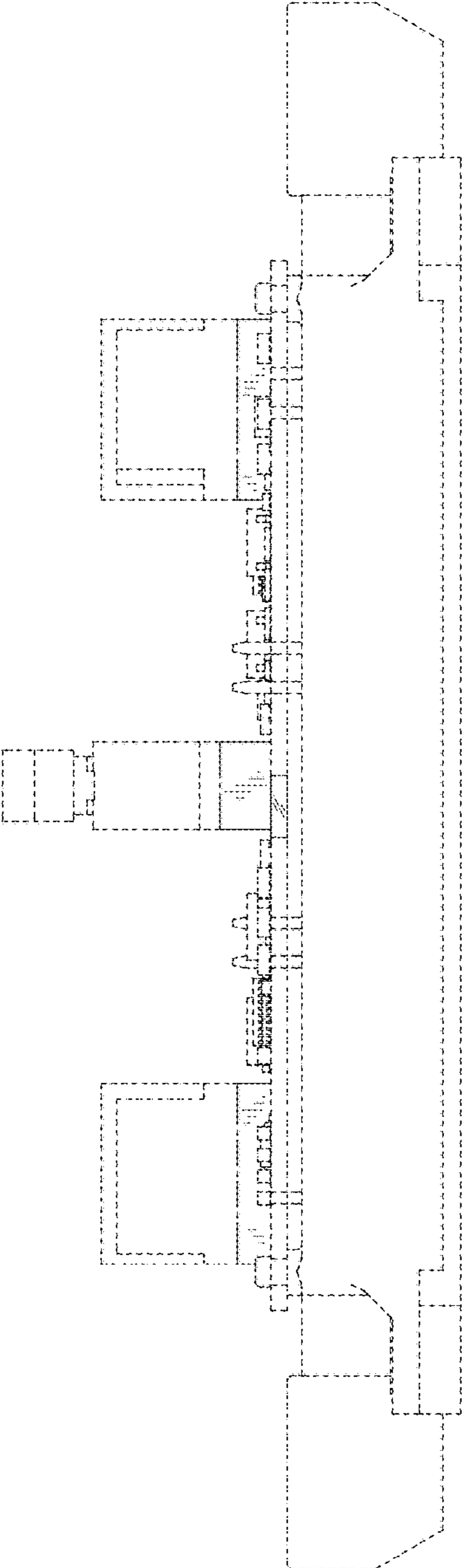


FIG.4

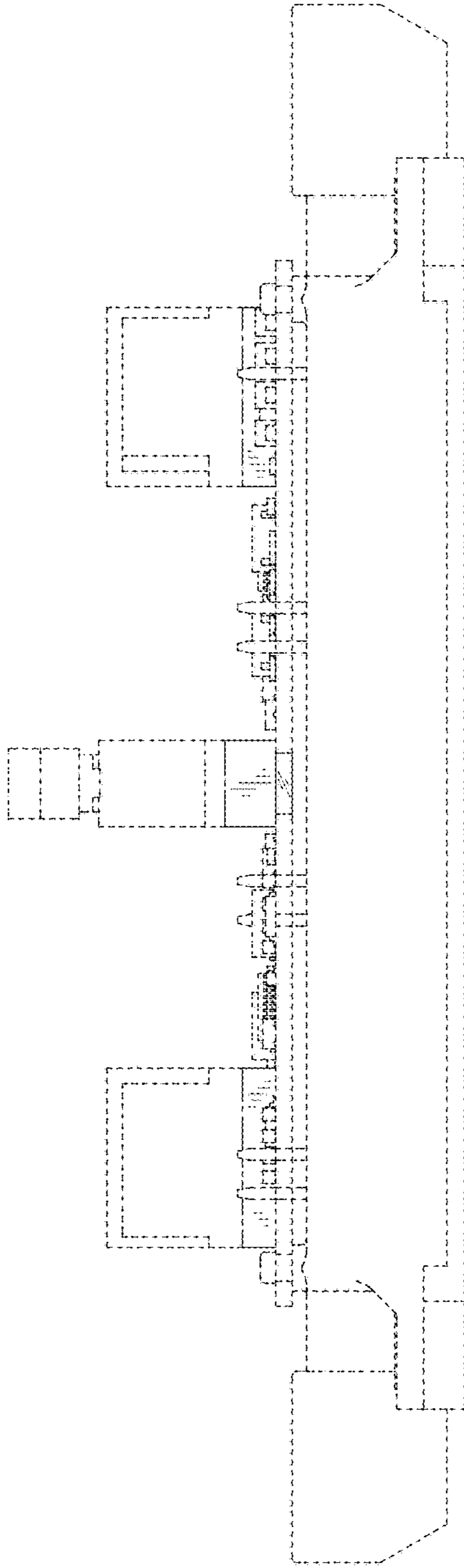


FIG.5

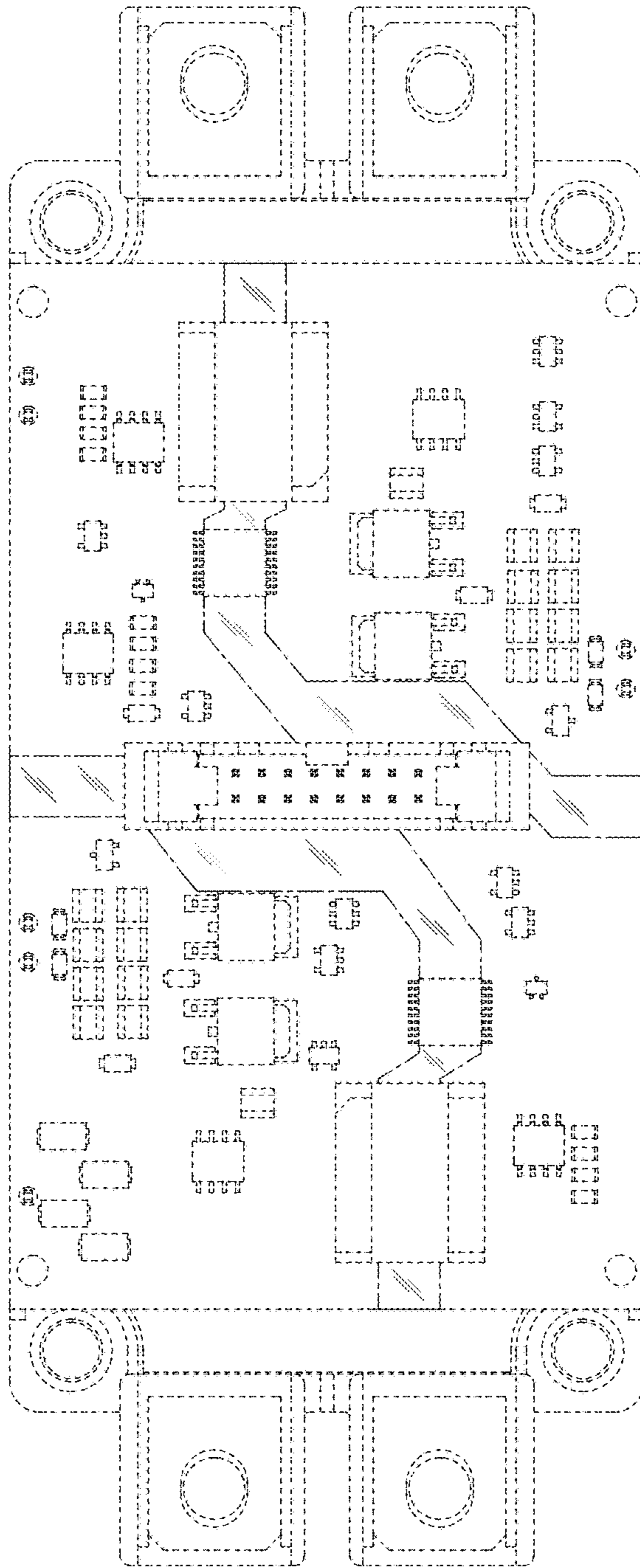


FIG.6

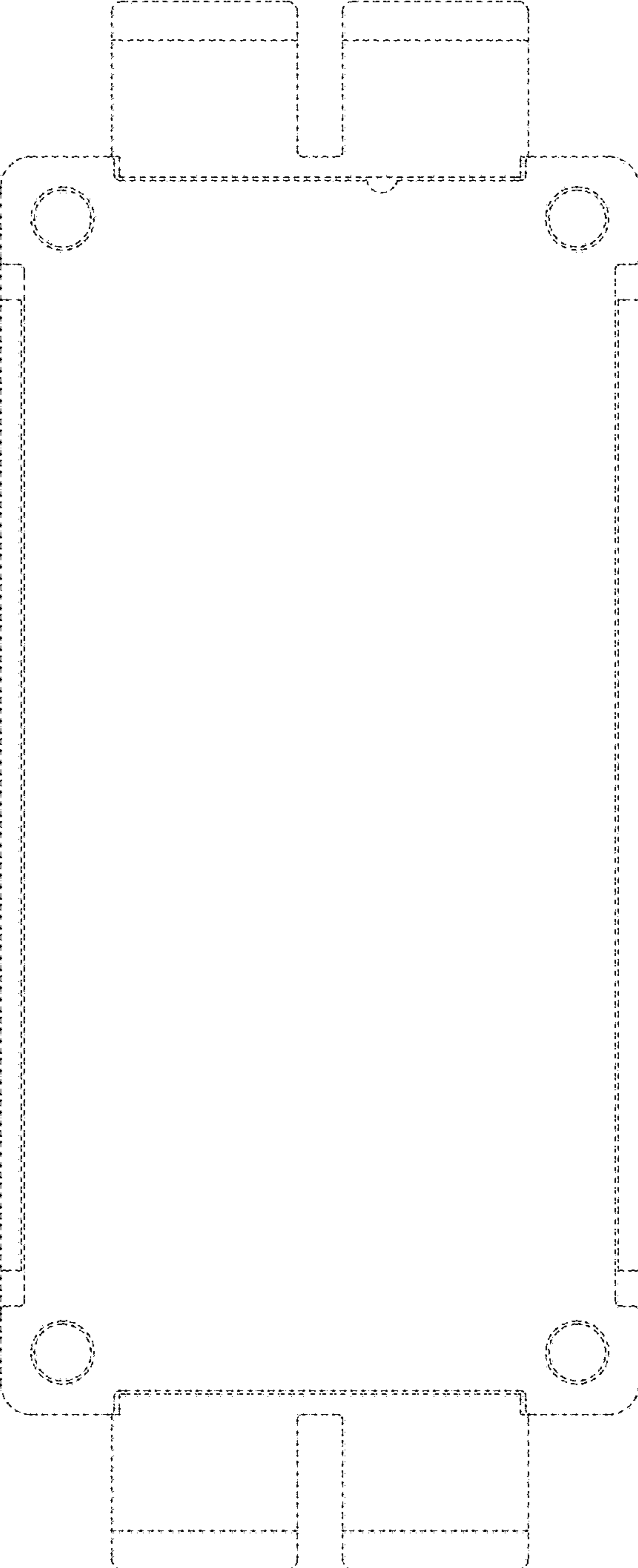


FIG.7

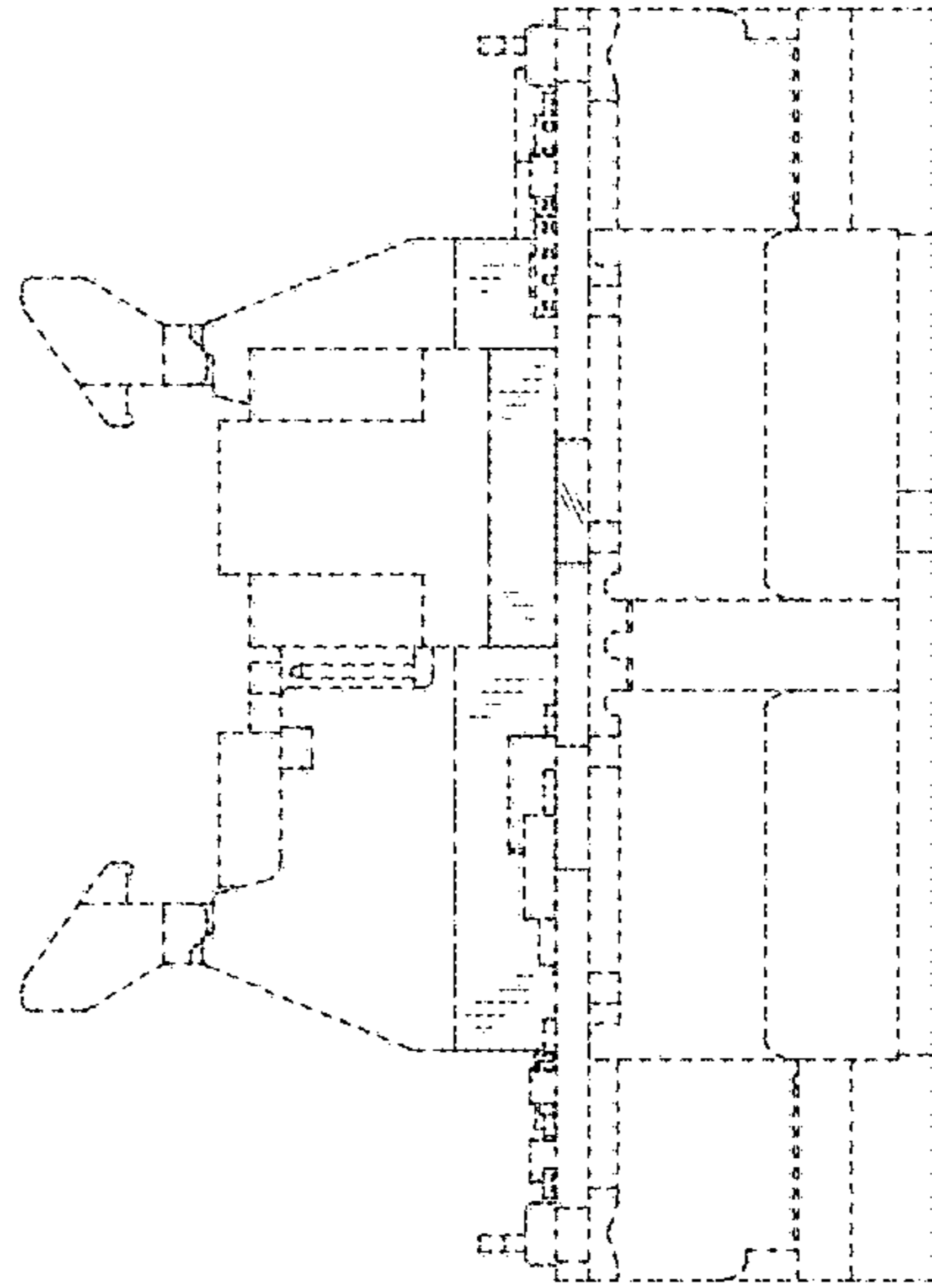


FIG. 8

